

Chapter 13

Mechanical Specifications

13.1 Introduction

This section describes the dimensions of the plastic dual in-line package (DIP), plastic shrink dual in-line package (SDIP), plastic leaded chip carrier (PLCC), and quad flat pack (QFP) MCU packages.

The following figures show the latest package drawings at the time of this publication. To make sure that you have the latest package specifications, contact your local Freescale Sales Office.

13.2 40-Pin Plastic Dual In-Line (DIP) Package (Case 711-03)

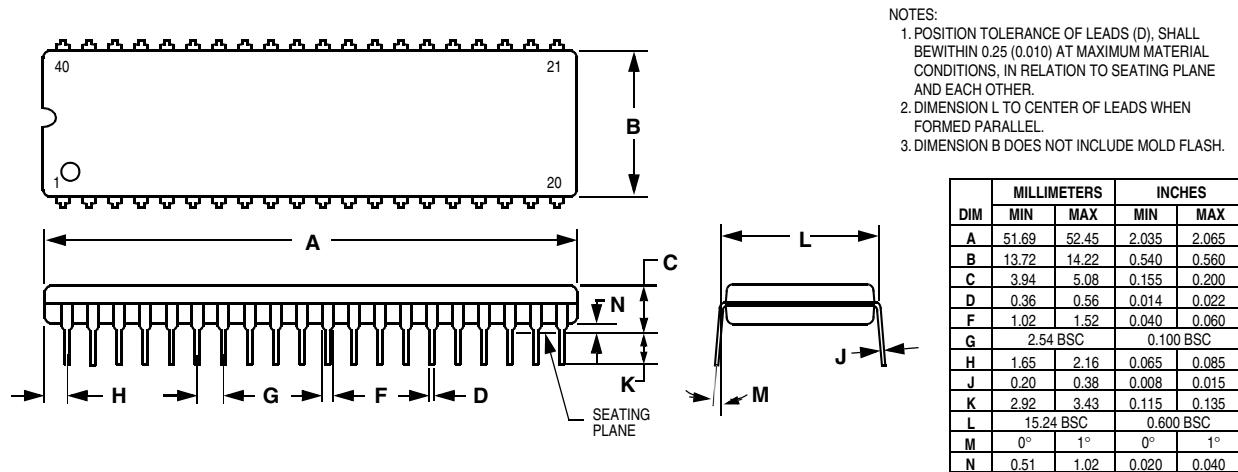


Figure 13-1. 40-Pin Plastic DIP Package (Case 711-03)